

SK 70 D



SEMITOP® 2

Bridge Rectifier

SK 70 D

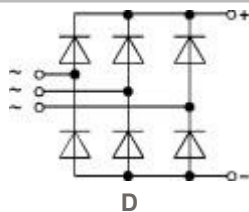
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and insulation through direct copper bonded aluminium oxide ceramic (DCB)
- Up to 1600V reverse voltage
- High surge currents
- Glass passivated diodes chips
- UL recognized, file no. E 63 532

Typical Applications

- Input rectifier for power supplies
- Rectifier



V_{RSM} V	V_{RRM}, V_{DRM} V	$I_D = 70 \text{ A (full cond.)}$ ($T_s = 80 \text{ °C}$)
800	800	SK 70 D 08
1200	1200	SK 70 D 12
1600	1600	SK 70 D 16

Symbol	Conditions
I_D	$T_s = 80 \text{ °C}$
I_{FSM}	$T_{vj} = 25 \text{ °C}; 10 \text{ ms}$ $T_{vj} = 150 \text{ °C}; 10 \text{ ms}$
i_{2t}	$T_{vj} = 25 \text{ °C}; 8,3...10 \text{ ms}$ $T_{vj} = 150 \text{ °C}; 8,3...10 \text{ ms}$
V_F	$T_{vj} = 25 \text{ °C}; I_F = 25 \text{ A}$
$V_{(TO)}$	$T_{vj} = 150 \text{ °C}$
r_T	$T_{vj} = 150 \text{ °C}$
I_{RD}	$T_{vj} = 150 \text{ °C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$
$R_{th(j-s)}$	per diode
T_{solder}	per module
T_{vj}	terminals, 10s
T_{stg}	
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.
M_s	mounting torque to heatsink
M_t	
m	approx. weight
Case	SEMITOP® 2

Diagrams

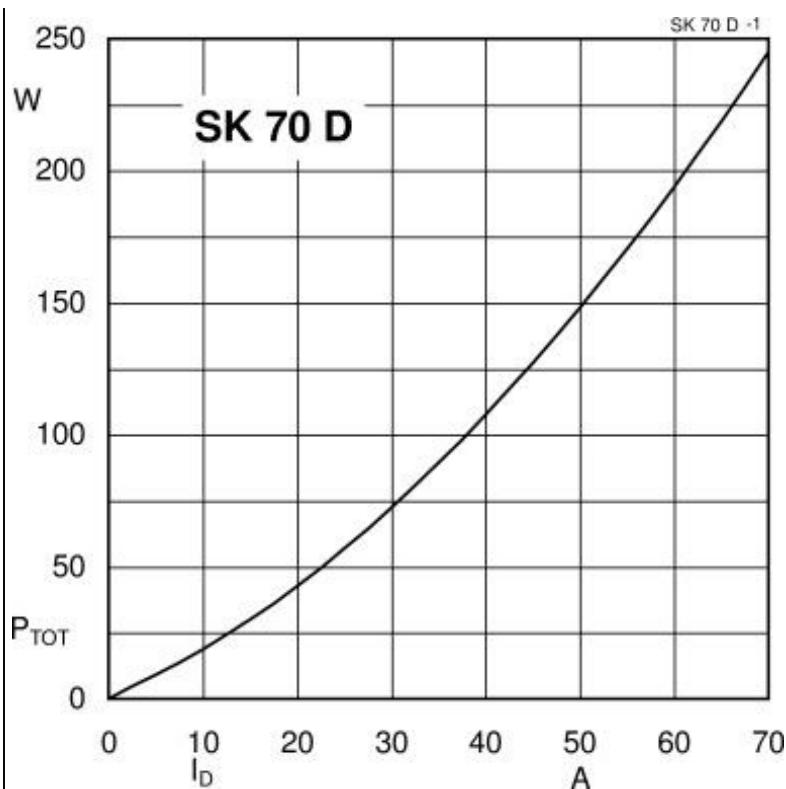


Fig. 1 Power dissipation vs. Output current

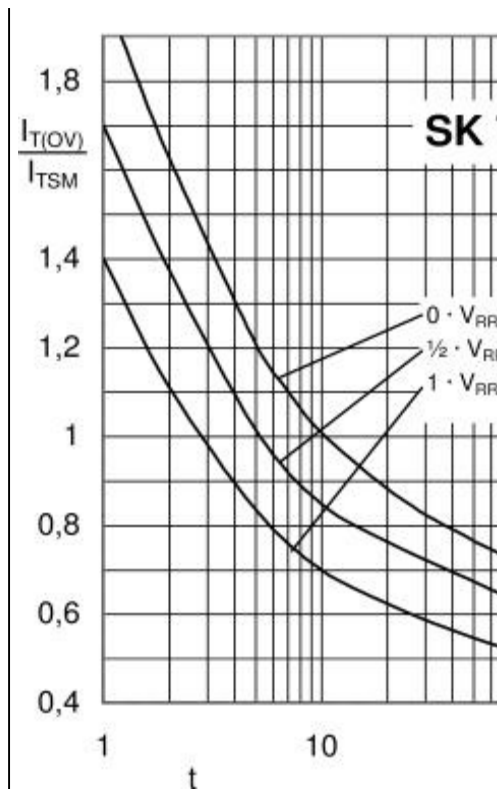


Fig. 2 Surge overload current vs. time

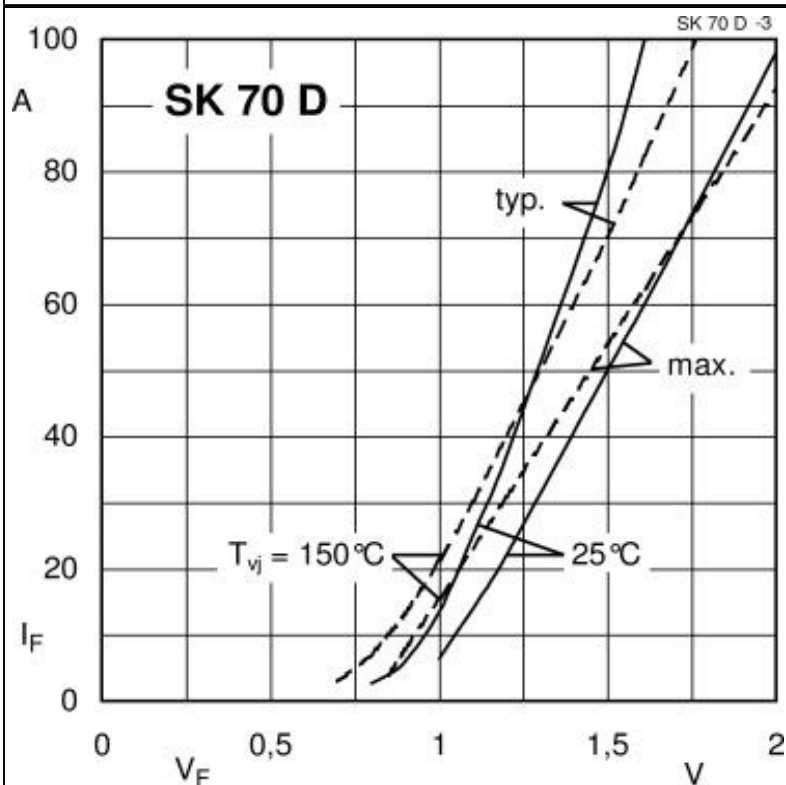


Fig. 3 Forward characteristics of single diode

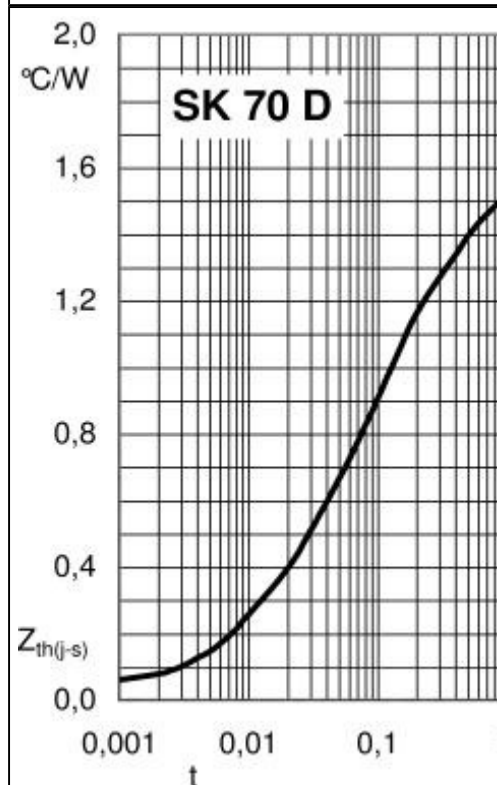
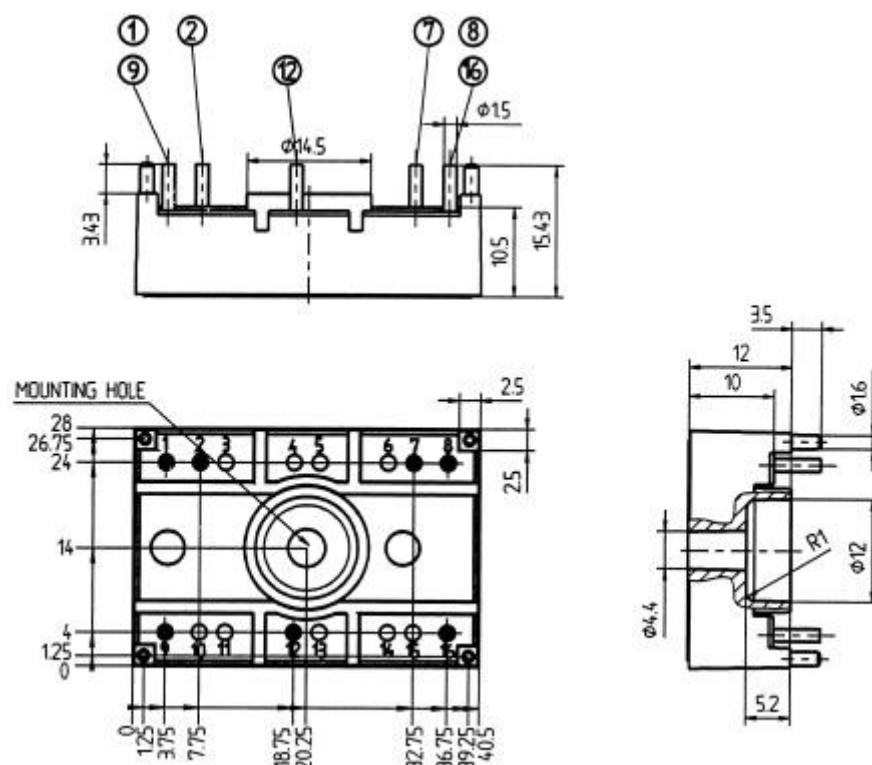


Fig. 4 Thermal transient impedance vs. time

Cases / Circuits

Dimensions in mm



Case T7 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins = 2mm)

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